



Material Content Data Sheet



Sales Product Name				BSZ165N04NS G		Issued		25. September 2017	
MA#				MA000469864					
Package				PG-TSDSON-8-1		Weight*		35.88 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.531	1.48	1.48	14794	14794	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		66		
	non noble metal	zinc	7440-66-6	0.009	0.03		264		
	non noble metal	iron	7439-89-6	0.189	0.53		5278		
wire	non noble metal	copper	7440-50-8	7.689	21.43	22.00	214328	219936	
	non noble metal	copper	7440-50-8	0.039	0.11	0.11	1097	1097	
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1055	
	plastics	epoxy resin	-	1.950	5.44		54354		
	inorganic material	silicondioxide	60676-86-0	16.943	47.21	52.76	472296	527705	
leadfinish	non noble metal	tin	7440-31-5	0.370	1.03	1.03	10316	10316	
plating	noble metal	silver	7440-22-4	0.081	0.23	0.23	2252	2252	
solder	noble metal	silver	7440-22-4	0.021	0.06		593		
	non noble metal	tin	7440-31-5	0.017	0.05		475		
	non noble metal	lead	7439-92-1	0.813	2.27	2.38	22667	23735	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33		
	non noble metal	zinc	7440-66-6	0.005	0.01		131		
	non noble metal	iron	7439-89-6	0.094	0.26		2620		
	non noble metal	copper	7440-50-8	3.816	10.64	10.91	106369	109153	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		109		
	non noble metal	iron	7439-89-6	0.078	0.22		2184		
	non noble metal	copper	7440-50-8	3.182	8.87	9.10	88692	91012	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com